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01/22/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10055266	01/22/2002	257	138	2811	Q. Vu

**APPLICANTS: Choi Ki-won;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:
REPUBLIC OF KOREA 2001-5945 02/07/2001PG-PUB DO NOT PUBLISH ☐RESCIND ☐Foreign priority claimed ☐ yes ☐ no35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

9898-208

TITLE : Semiconductor package having changed substrate design using special wire bonding

U.S. DEPT. OF COMM /PAT & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner			
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawg.	Figs Drawg. Print Fig.
		Primary Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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